Altatech

High-speed wafer inspection

AltaSight® is based on a unique, patented full-field optical technology. This enables a high-efficiency inspection equipment concept at high throughput.

AltaSight® SL300 offers technology for whole surface inspection (frontside, backside and edge). From wafer lapping to final inspection or incoming quality check, this unique technology combination grants you a wide point of view on your wafer or process.

Features

- 300 mm, full wafer coverage
- Throughput at 100 WPH
- Topographical sensitivity in nanometer range
- Class 1 measurement chamber
- Smart design for easy maintenance
- Defect map correlation between wafer frontside and backside
- ASE and KLARF output support
- Defect picture recording for offline review
- Low cost of ownership

photo: © O. Dupont

Altatech

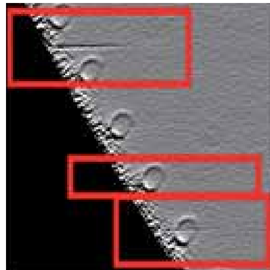
611 rue Aristide Bergès, Z.A. de Pré Millet
38330 MONTBONNOT-SAINT-MARTIN (France)
Tel. +33 (0)456 526 800 - Fax +33 (0)456 526 801
www.altatech-sc.com

Technology

- Surface topography and reflectivity inspection
- Phase-shift-based method
- Full wafer acquisition
- Automated defect classification (ADC)
- SEMI standards compliant

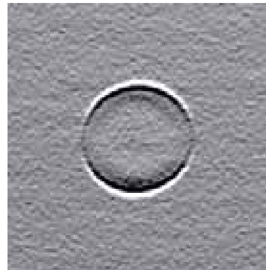
Results

Detection of cracks, scratches, contamination areas and more.



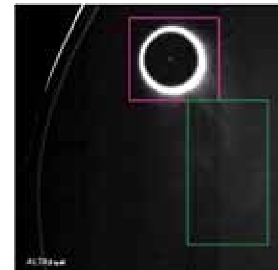
Epi process monitoring

Slip-line detection, backside inspection and wafer-chuck fingerprint monitoring



Backside damage detection

Wafer surface damage from chuck pin



Darkfield inspection

Applications

- Automated macro inspection
- Visual inspection replacement
- Output/input quality check
- Engineered-substrate process monitoring
- Defect map correlation between wafer frontside & backside
- Wafer-chuck fingerprint monitoring
- Detecting handling damage
- Detecting thermal/mechanical process-induced defects
- Inspecting TSVs, backsides and edges on transparent substrates

design: VHOX.com | AltaSight and AltaSight EyeEdge are registered trademarks of Altatech Semiconductor | © Altatech Semiconductor - October 2010